PROCEEDINGS OF SPIE

Dimensional Optical Metrology and Inspection for Practical Applications III

Kevin G. Harding
Toru Yoshizawa
Song Zhang
Editors

5–6 May 2014
Baltimore, Maryland, United States

Sponsored and Published by
SPIE

Volume 9110

Proceedings of SPIE 0277-786X, V. 9110

SPIE is an international society advancing an interdisciplinary approach to the science and application of light.

Dimensional Optical Metrology and Inspection for Practical Applications III, edited by
Kevin G. Harding, Toru Yoshizawa, Song Zhang, Proc. of SPIE Vol. 9110, 911001
© 2014 SPIE · CCC code: 0277-786X/14/$18 · doi: 10.1117/12.2072208

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Author(s), "Title of Paper," in *Dimensional Optical Metrology and Inspection for Practical Applications III*, edited by Kevin G. Harding, Toru Yoshizawa, Song Zhang, Proceedings of SPIE Vol. 9110 (SPIE, Bellingham, WA, 2014) Article CID Number.

ISSN: 0277-786X
ISBN: 9781628410471

Published by
SPIE
P.O. Box 10, Bellingham, Washington 98227-0010 USA
Telephone +1 360 676 3290 (Pacific Time) · Fax +1 360 647 1445
SPIE.org

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Introduction

The field of Optical Metrology for Practical Applications continues to grow with the needs of the manufacturing and service communities need for more complete information. Structured light continues to be a core method for many applications with papers in this volume addressing how to reduce projector noise, improve calibration, and improve speed. Some applications covered in this volume include LED manufacturing, pipe inspection, material characterization, semiconductor manufacturing, and surface metrology. The papers presented in this volume represent many of the current and future state-of-the-art instruments of the metrology industry.

Kevin G. Harding
Toru Yoshizawa